Integrated Device Technology, Inc.

3.3V CMOS 16-BIT BUS TRANSCEIVER/REGISTER WITH 3-STATE OUTPUTS, 5 VOLT TOLERANT, BUS-HOLD

IDT74LVCH162646A
ADVANCE INFORMATION

FEATURES:

- Typical $t_{SK(o)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP and 0.40mm pitch TVSOP packages
- Extended commercial range of -40°C to +85°C
- V_{CC} = 3.3V ±0.3V, Normal Range
- V_{CC} = 2.7V to 3.6V, Extended Range
- CMOS power levels (0.4µW typ. static)
- All inputs, outputs and I/O are 5 Volt tolerant
- Supports hot insertion

Drive Features for LVCH162646A:

- Balanced Output Drivers: ±12mA
- Low switching noise

APPLICATIONS:

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

DESCRIPTION:

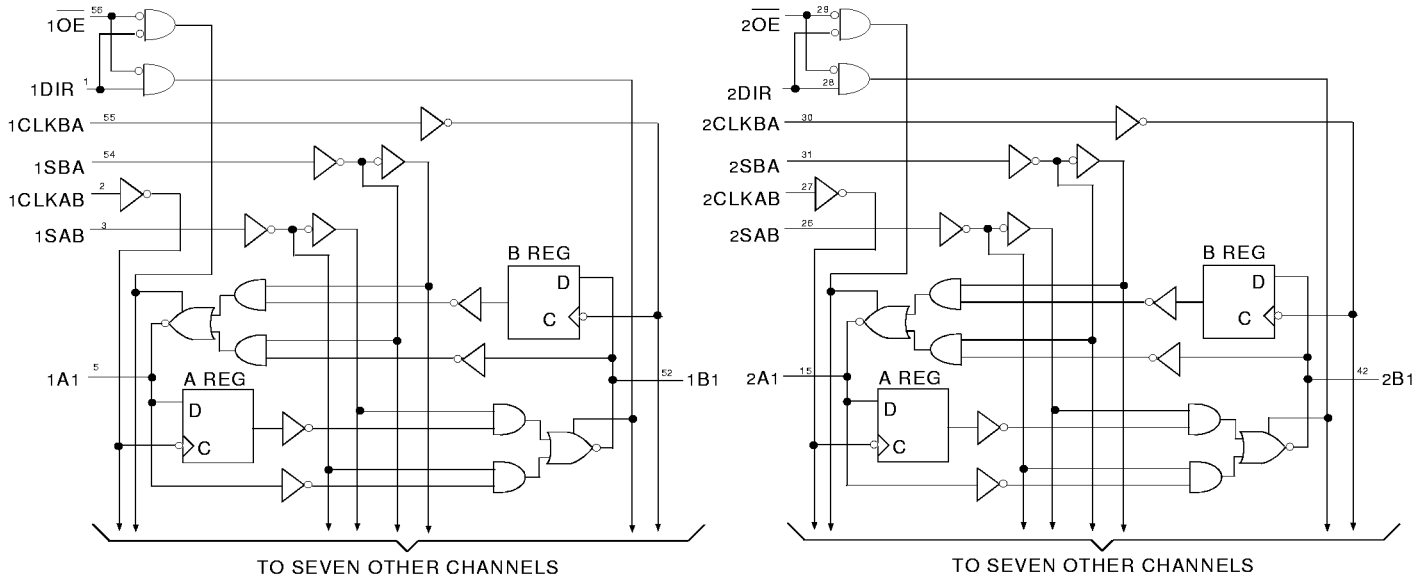
The LVCH162646A 16-bit transceiver/register is built using advanced dual metal CMOS technology. This high-speed, low power device is organized as two independent 8-bit D-type transceivers with 3-state D-type registers. The controls circuitry is organized for multiplexed transmission of data between A bus and B bus either directly or from the internal storage registers. Each 8-bit transceiver/register features direction control (DIR), over-riding Output Enable control ($\overline{OE}$) and Select lines (SAB and SBA) to select either real-time data or stored data. Separate clock inputs are provided for A and B port registers. Data on the A or B data bus, or both, can be stored in the internal registers by the low-to-high transitions at the appropriate clock pins. Flow-through organization of signal pins simplifies layout. All inputs are designed with hysteresis for improved noise margin.

All pins can be driven from either 3.3V or 5V devices. This feature allows the use of this device as a translator in a mixed 3.3V/5V supply system.

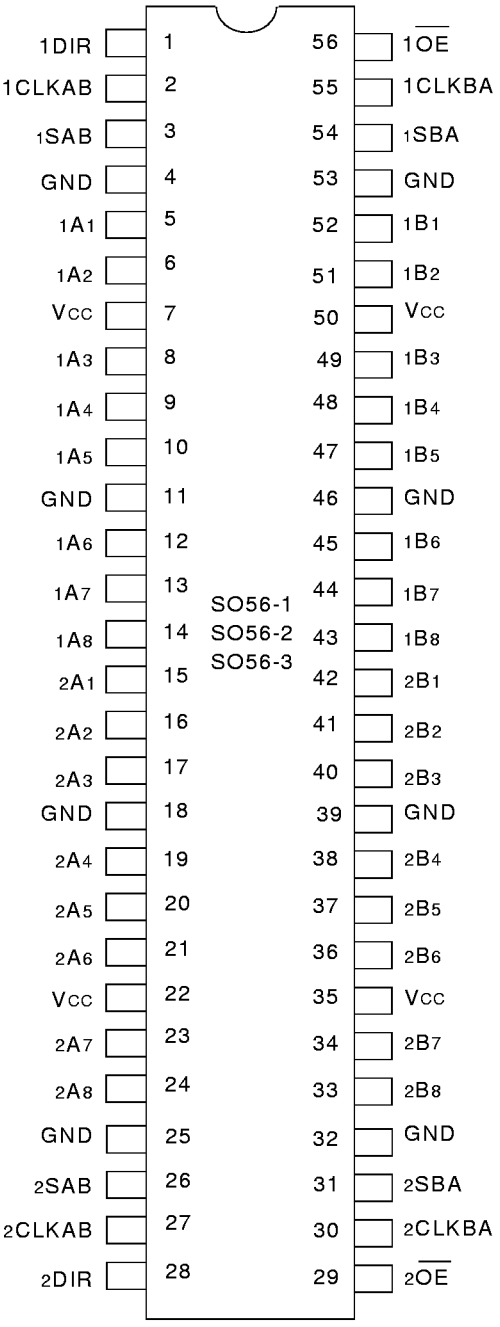
The LVCH162646A has series resistors in the device output structure which will significantly reduce line noise when used with light loads. This driver has been developed to drive ±12mA at the designated threshold levels.

The LVCH162646A has "bus-hold" which retains the inputs' last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION



SSOP/ TSSOP/TVSOP TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max.	Unit
V_{TERM}(2)	Terminal Voltage with Respect to GND	– 0.5 to +6.5	V
V_{TERM}(3)	Terminal Voltage with Respect to GND	– 0.5 to +6.5	V
T_{STG}	Storage Temperature	– 65 to +150	°C
I_{OUT}	DC Output Current	– 50 to +50	mA
I_{IK} I_{OK}	Continuous Clamp Current, $V_I < 0$ or $V_O < 0$	– 50	mA
I_{CC} I_{SS}	Continuous Current through each V_{CC} or GND	±100	mA

LVC Link

NOTES:
1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. V_{CC} terminals.
3. All terminals except V_{CC}.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

Symbol	Parameter(1)	Conditions	Typ.	Max.	Unit
C_{IN}	Input Capacitance	V_{IN} = 0V	4.5	6	pF
C_{OUT}	Output Capacitance	V_{OUT} = 0V	6.5	8	pF
$C_{I/O}$	I/O Port Capacitance	V_{IN} = 0V	6.5	8	pF

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NOTE:
1. As applicable to the device type.

PIN DESCRIPTION

Pin Names	Description
xAx	Data Register A Inputs(1) Data Register B Outputs
xBx	Data Register B Inputs(1) Data Register A Outputs
xCLKAB, xCLKBA	Clock Pulse Inputs
xSAB, xSBA	Output Data Source Select Inputs
$x\overline{OE}$	Output Enable Inputs (Active LOW)
xDIR	Direction Control Inputs

NOTE:
1. These pins have "Bus-hold". All other pins are standard inputs, outputs, or I/Os.

FUNCTION TABLE (1)

Inputs						Data I/O(2)		
$x\overline{OE}$	xDIR	xCLKAB	xCLKBA	xSAB	xSBA	xAx	xBx	Operation or Function
X	X	↑	X	X	X	Input	Unspecified	Store A, B unspecified (2)
X	X	X	↑	X	X	Unspecified	Input	Store B, A unspecified (2)
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	H or L	H or L	X	X	Input	Input	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
L	H	X	X	L	X	Input	Output	Real-time data to B bus
L	H	H or L	X	H	X	Input	Output	Stored A data to bus

NOTES:
1. H = HIGH Voltage Level
   L = LOW Voltage Level
   X = Don't Care
   ↑ = Low-to-High Transition
2. The data-output functions may be enabled or disabled by various signals at $\overline{OE}$ or DIR. Data-input functions always are enabled, i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:
Operating Condition: T_A = –40°C to +85°C

Symbol	Parameter	Test Conditions		Min.	Typ.(1)	Max.	Unit
V_{IH}	Input HIGH Voltage Level	V_{CC} = 2.3V to 2.7V		1.7	—	—	V
		V_{CC} = 2.7V to 3.6V		2	—	—	
V_{IL}	Input LOW Voltage Level	V_{CC} = 2.3V to 2.7V		—	—	0.7	V
		V_{CC} = 2.7V to 3.6V		—	—	0.8	
I_{IH} I_{IL}	Input Leakage Current	V_{CC} = 3.6V	V_I = 0 to 5.5V	—	—	±5	µA
I_{OZH} I_{OZL}	High Impedance Output Current (3-State Output pins)	V_{CC} = 3.6V	V_O = 0 to 5.5V	—	—	±10	µA
I_{OFF}	Input/Output Power Off Leakage	V_{CC} = 0V, V_{IN} or V_O ≤5.5V		—	—	±50	µA
V_{IK}	Clamp Diode Voltage	V_{CC} = 2.3V, I_{IN} = – 18mA		—	– 0.7	– 1.2	V
V_H	Input Hysteresis	V_{CC} = 3.3V		—	100	—	mV
I_{CCL} I_{CCH} I_{CCZ}	Quiescent Power Supply Current	V_{CC} = 3.6V	V_{IN} = GND or V_{CC}	—	—	10	µA
			3.6 ≤ V_{IN} ≤ 5.5V(2)	—	—	10	
ΔI_{CC}	Quiescent Power Supply Current Variation	One input at V_{CC} - 0.6V other inputs at V_{CC} or GND		—	—	500	µA

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NOTES:
1. Typical values are at V_{CC} = 3.3V, +25°C ambient.
2. This applies in the disabled state only.

BUS HOLD CHARACTERISTICS

Symbol	Parameter(1)	Test Conditions		Min.	Typ.(2)	Max.	Unit
I_{BHH}	Bus-Hold Input Sustain Current	V_{CC} = 3.0V	V_I = 2.0V	– 75	—	—	µA
I_{BHL}			V_I = 0.8V	75	—	—	
I_{BHH}	Bus-Hold Input Sustain Current	V_{CC} = 2.3V	V_I = 1.7V	—	—	—	µA
I_{BHL}			V_I = 0.7V	—	—	—	
I_{BHHO} I_{BHLO}	Bus-Hold Input Overdrive Current	V_{CC} = 3.6V	V_I = 0 to 3.6V	—	—	± 500	µA

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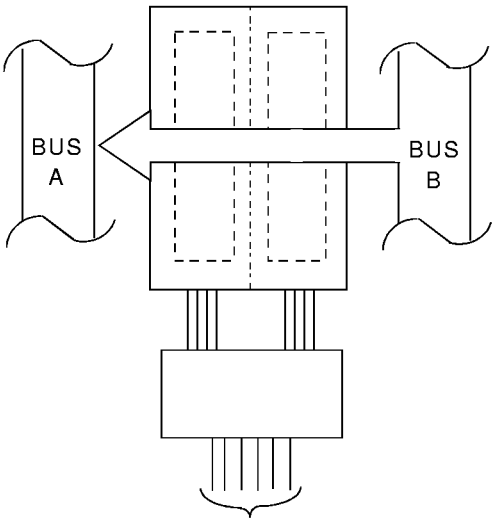
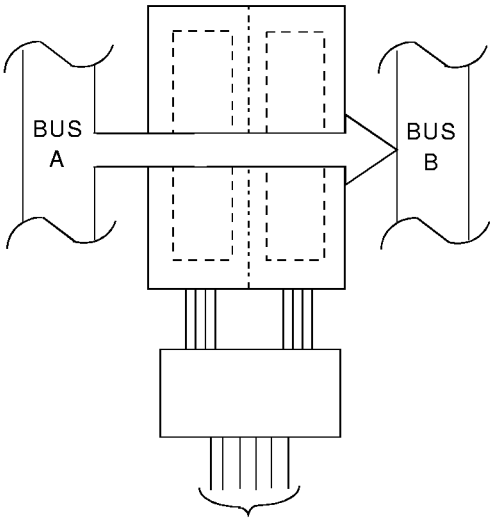
NOTES:
1. Pins with Bus-hold are identified in the pin description.
2. Typical values are at V_{CC} = 3.3V, +25°C ambient.



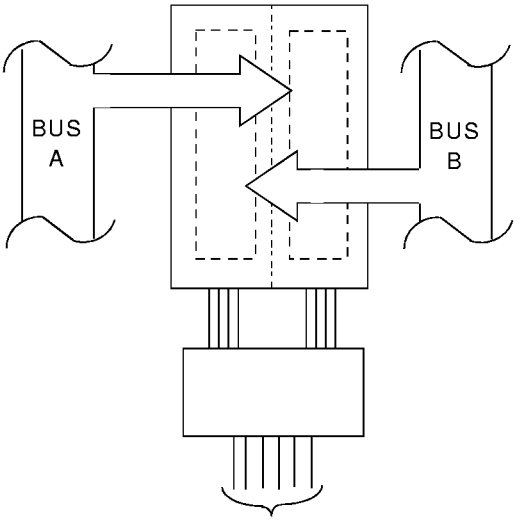
xDIR	$\overline{xOE}$	xCLKAB	xCLKBA	xSAB	xSBA
L	L	X	X	X	L

REAL-TIME TRANSFER
BUS B TO A



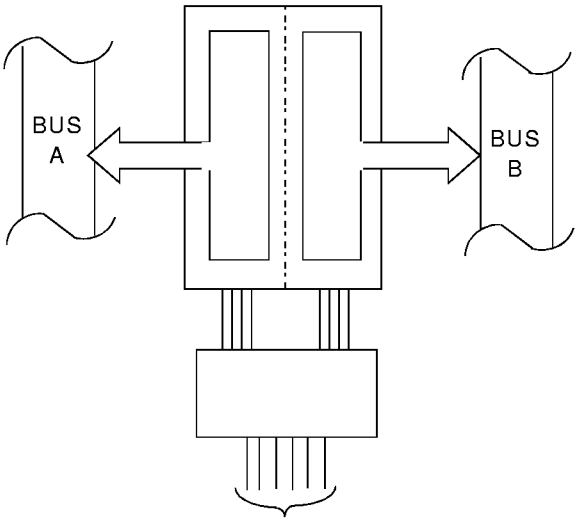
xDIR	$\overline{xOE}$	xCLKAB	xCLKBA	xSAB	xSBA
H	L	X	X	L	X

REAL-TIME TRANSFER
BUS A TO B



xDIR	$\overline{xOE}$	xCLKAB	xCLKBA	xSAB	xSBA
H	L	↑	X	X	X
L	L	X	↑	X	X
X	H	↑	↑	X	X

STORAGE FROM
A, B, OR A AND B



xDIR[(1)]	$\overline{xOE}$	xCLKAB	xCLKBA	xSAB	xSBA
L	L	X	H or L	X	H
H	L	H or L	X	H	X

TRANSFER STORED
DATA TO A AND/OR B

NOTE:
1. Cannot transfer data to A Bus and B Bus simultaneously..

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions[1]		Min.	Max.	Unit
V_{OH}	Output HIGH Voltage	V_{CC} = 2.3V to 3.6V	I_{OH} = –0.1mA	V_{CC} – 0.2	—	V
		V_{CC} = 2.3V	I_{OH} = –4mA	1.9	—	
			I_{OH} = –6mA	1.7	—	
		V_{CC} = 2.7V	I_{OH} = –4mA	2.2	—	
			I_{OH} = –8mA	2	—	
		V_{CC} = 3.0V	I_{OH} = –6mA	2.4	—	
			I_{OH} = –12mA	2	—	
V_{OL}	Output LOW Voltage	V_{CC} = 2.3V to 3.6V	I_{OL} = 0.1mA	—	0.2	V
		V_{CC} = 2.3V	I_{OL} = 4mA	—	0.4	
			I_{OL} = 6mA	—	0.55	
		V_{CC} = 2.7V	I_{OL} = 4mA	—	0.4	
			I_{OL} = 8mA	—	0.6	
		V_{CC} = 3.0V	I_{OL} = 6mA	—	0.55	
			I_{OL} = 12mA	—	0.8	

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NOTE:

1. V_{IH} and V_{IL} must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V_{CC} range. T_A = –40°C to +85°C.

OPERATING CHARACTERISTICS, V_{CC} = 3.3V ± 0.3V, T_A = 25°C

Symbol	Parameter	Test Conditions	Typical	Unit
C_{PD}	Power Dissipation Capacitance per transceiver Outputs enabled	C_L = 0pF, f = 10Mhz	—	pF
C_{PD}	Power Dissipation Capacitance per transceiver Outputs disabled		—	pF

SWITCHING CHARACTERISTICS (1)

Symbol	Parameter	Vcc = 2.7V		Vcc = 3.3V ± 0.3V		Unit
		Min.	Max.	Min.	Max.	
t_{PLH} t_{PHL}	Propagation Delay xAx to xBx or xBx to xAx	2	6.3	2	5.3	ns
t_{PLH} t_{PHL}	Propagation Delay CLK to xAx or xBx	2	7.3	2	6.3	ns
t_{PLH} t_{PHL}	Propagation Delay xSBA or xSAB to xAx or xBx	2	7.3	2	6.3	ns
t_{PZH} t_{PZL}	Output Enable Time x$\overline{OE}$ to xAx or xBx	2	8.5	2	7.5	ns
t_{PZH} t_{PZL}	Output Enable Time xDIR to xAx or xBx	2	8.5	2	7.5	ns
t_{PHZ} t_{PLZ}	Output Disable Time x$\overline{OE}$ to xAx or xBx	2	7	2	6	ns
t_{PHZ} t_{PLZ}	Output Disable Time xDIR to xAx or xBx	2	7	2	6	ns
t_{SU}	Set-up Time HIGH or LOW Before CLKAB↑ or CLKBA↑	2.5	—	2.5	—	ns
t_H	Hold Time HIGH or LOW After CLKAB↑ or CLKBA↑	1.5	—	1.5	—	ns
t_W	Clock Pulse Width HIGH or LOW	3	—	3	—	ns
$t_{SK(o)}$	Output Skew(2)	—	—	—	500	ps

NOTES:
1. See test circuits and waveforms. $T_A = -40°C$ to $+85°C$.
2. Skew between any two outputs of the same package and switching in the same direction.

TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	$V_{CC}^{(1)}$ = 3.3V ±0.3V	$V_{CC}^{(1)}$ = 2.7V	$V_{CC}^{(2)}$ = 2.5V ±0.2V	Unit
V_{LOAD}	6	6	2 x Vcc	V
V_{IH}	2.7	2.7	Vcc	V
V_T	1.5	1.5	Vcc / 2	V
V_{LZ}	300	300	150	mV
V_{HZ}	300	300	150	mV
C_L	50	50	30	pF

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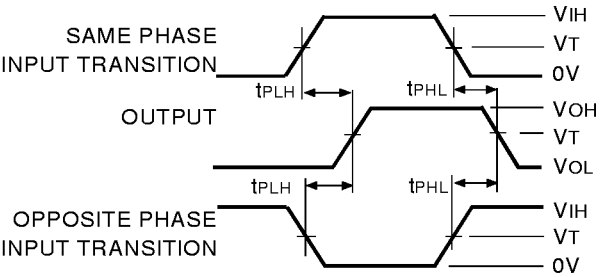
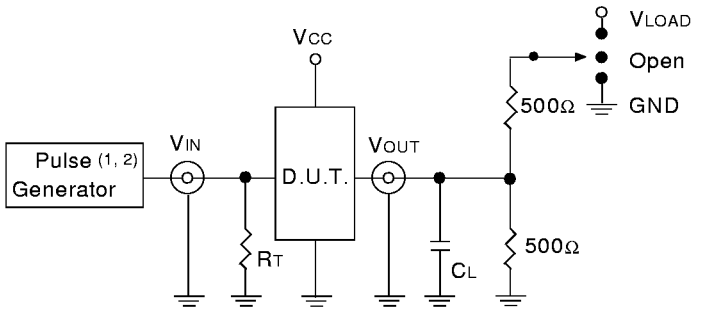
PROPAGATION DELAY



LVC Link

TEST CIRCUITS FOR ALL OUTPUTS



LVC Link

DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.
R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTE:

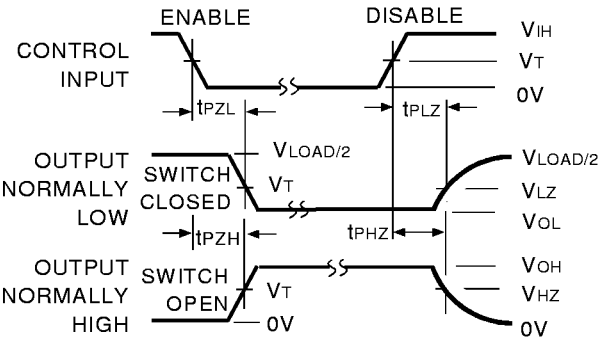
1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2.5ns; t_R ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_F ≤ 2ns; t_R ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	V_{LOAD}
Disable High Enable High	GND
All Other tests	Open

LVC Link

ENABLE AND DISABLE TIMES

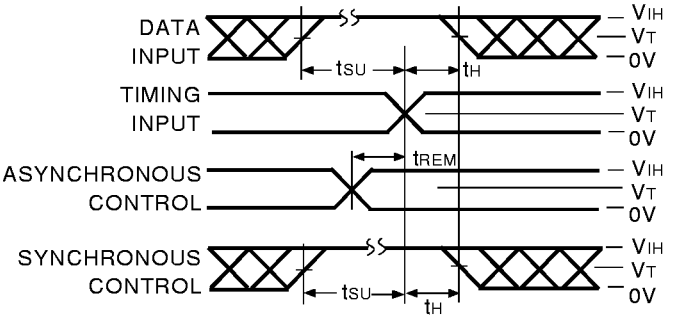


LVC Link

NOTE:

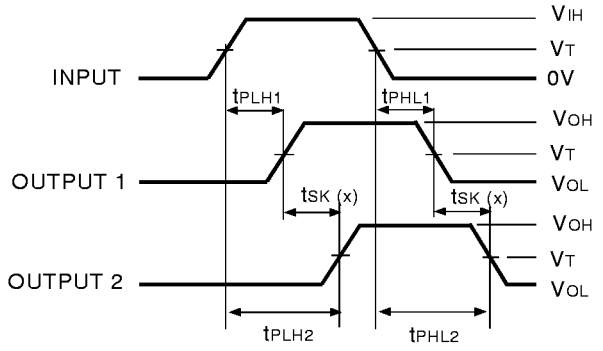
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD AND RELEASE TIMES



LVC Link

OUTPUT SKEW - t_{SK} (x)



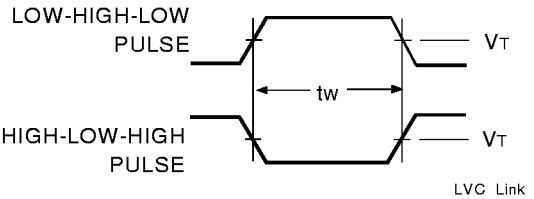
$t_{SK(x)} = |t_{PLH2} - t_{PLH1}|$ or $|t_{PHL2} - t_{PHL1}|$

LVC Link

NOTES:

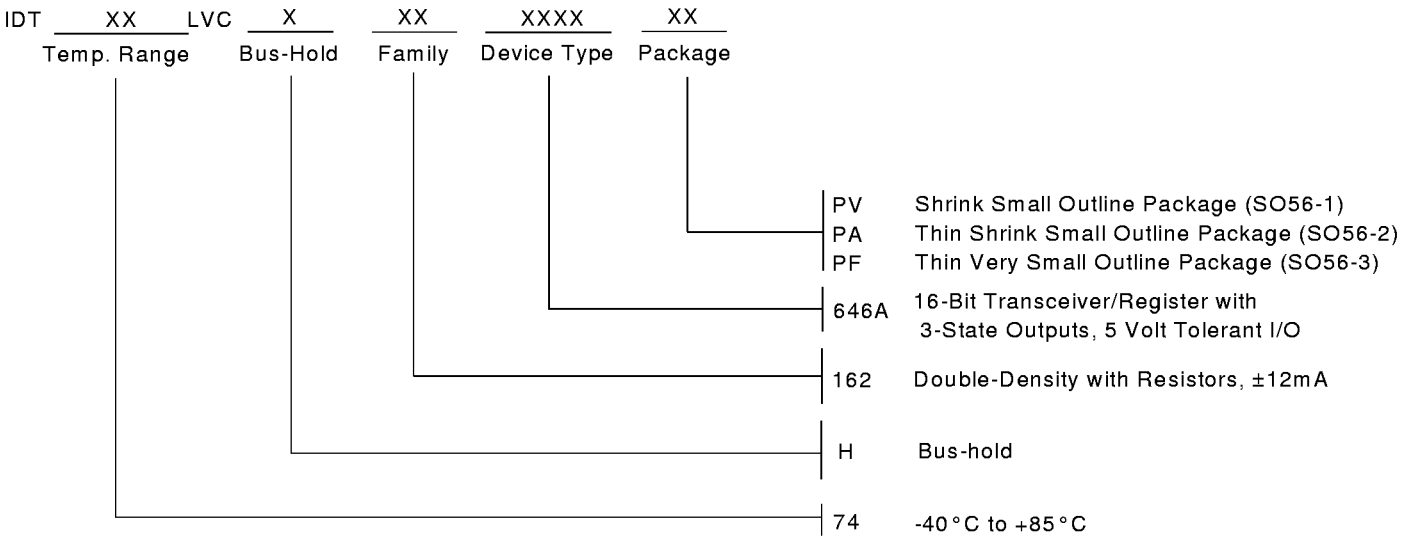
1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

PULSE WIDTH



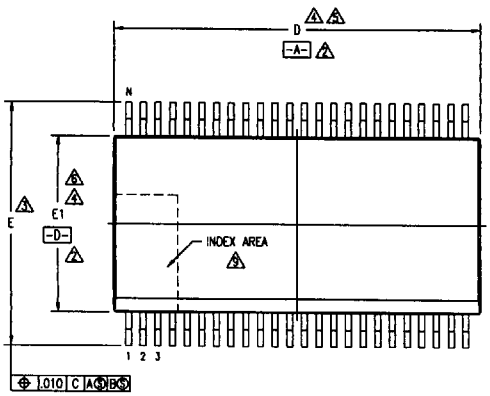
LVC Link

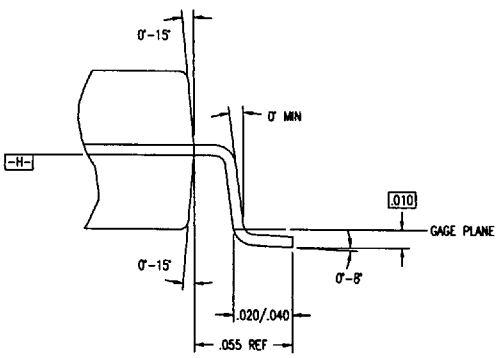
ORDERING INFORMATION



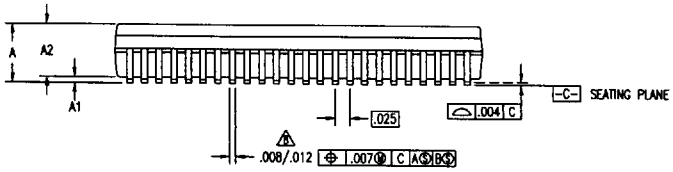
SSOP

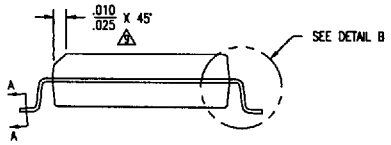
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. VU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	

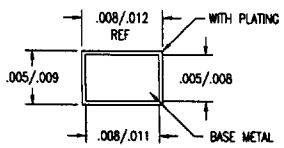




DETAIL B







SECTION A-A

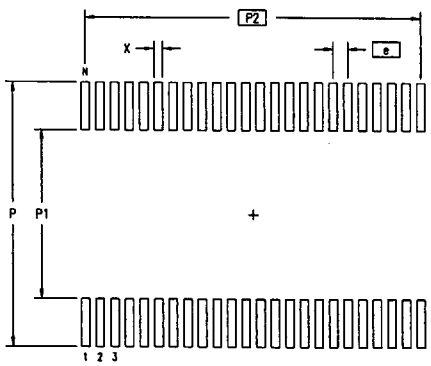
TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674 TWX: 910-338-2070	
DECIMAL XX± XXX± XXXX±	ANGULAR ±		
APPROVALS	DATE	TITLE PV PACKAGE OUTLINE .300" BODY WIDTH SSOP .025" PITCH	
DRAWN AA	08/15/90		
CHECKED		SIZE C	DRAWING No. PSC-4029 REV 02
		DO NOT SCALE DRAWING	

SSOP (Continued)

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
17893	00	INITIAL RELEASE	07/15/90	A. FUNCELL
22377	01	REMOVE CHAMFER FROM PACKAGE	04/15/92	T. VU
27492	02	REDRAW TO JEDEC FORMAT	02/01/95	

DWG #		S048-1			DWG #		S056-1		
SYMBOL	JEDEC VARIATION AA			NOTE	JEDEC VARIATION AB			NOTE
	MIN	NOM	MAX		MIN	NOM	MAX	
A	.095	.102	.110		.095	.102	.110	
A1	.008	.012	.016		.008	.012	.016	
A2	.088	.090	.092		.088	.090	.092	
D	.620	.625	.630	4,5	.720	.725	.730	4,5
E	.395	.405	.420	3	.395	.405	.420	3
E1	.291	.295	.299	4,6	.291	.295	.299	4,6
N	48				56			

LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX
P	.450	.458	.450	.458
P1	.282	.290	.282	.290
P2	.575 BSC		.675 BSC	
X	.010	.018	.010	.018
e	.025 BSC		.025 BSC	
N	48		56	

NOTES:

1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982

2 DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-

3 DIMENSION E TO BE DETERMINED AT SEATING PLANE -C-

4 DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE -H-

5 DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED .006 PER SIDE

6 DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .015 PER SIDE

7 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND .010 FROM LEAD TIP

8 LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .004 IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT

9 THE CHAMFER ON THE PACKAGE BODY IS OPTIONAL. IF IT IS NOT PRESENT, A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE ZONE INDICATED

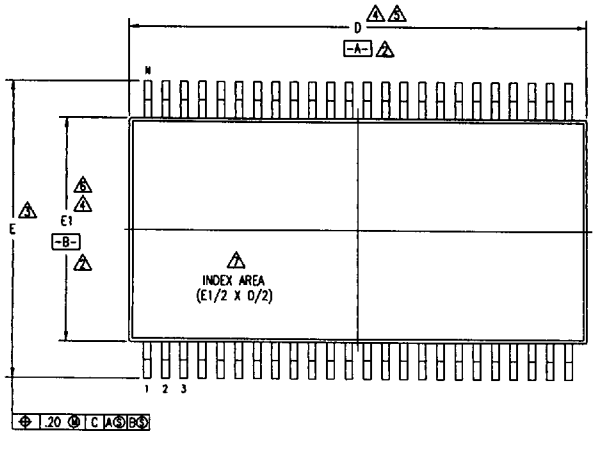
10 ALL DIMENSIONS ARE IN INCHES

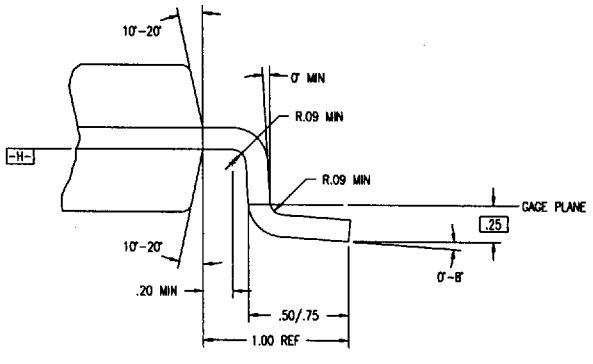
11 THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-118, VARATION AA & AB

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.
DECIMAL XX± XXX± XXXX±	ANGULAR ±	2975 Stender Way, Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674 TWX: 910-338-2070
APPROVALS	DATE	TITLE PV PACKAGE OUTLINE .300" BODY WIDTH SSOP .025" PITCH
DRAWN AA	05/15/90	
CHECKED		SIZE C DRAWING No. PSC-4029 REV 02
		DO NOT SCALE DRAWING

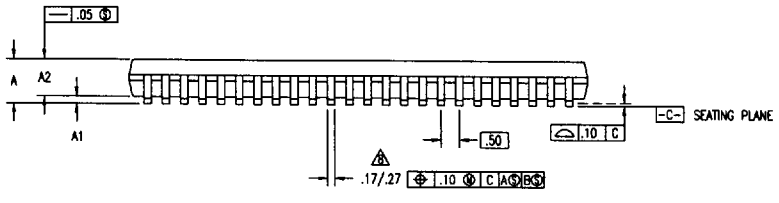
TSSOP

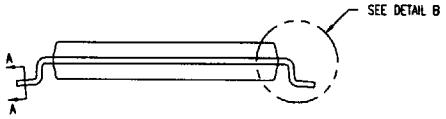
REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
25490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	

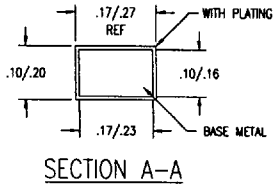




DETAIL B







SECTION A-A

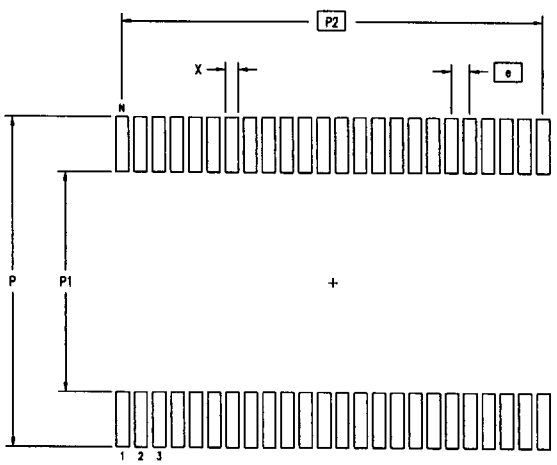
TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc. 2975 Stender Way, Santa Clara, CA 95054 PHONE: (408) 727-6116 FAX: (408) 492-8674 TWX: 910-338-2070	
DECIMAL	ANGULAR		
XX±	±		
XXX±			
XXXX±			
APPROVALS	DATE	TITLE	PA PACKAGE OUTLINE 6.10 mm BODY WIDTH TSSOP .50 mm PITCH
DRAWN dd	01/15/93		
CHECKED		SIZE C	DRAWING No. PSC-4039 REV 03
		DO NOT SCALE DRAWING	

TSSOP (Continued)

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
23757	00	INITIAL RELEASE	02/15/93	T. VU
26315	01	CHANGE DIMS A1 & A2	05/18/94	DG
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	

DWG #			S048-2		DWG #			S056-2	
SYMBOL	JEDEC VARIATION ED			NOTE	JEDEC VARIATION EE			NOTE
	MIN	NOM	MAX		MIN	NOM	MAX	
A	–	–	1.10		–	–	1.10	
A1	.05	–	.15		.05	–	.15	
A2	.85	1.00	1.05		.85	1.00	1.05	
D	12.40	12.50	12.60	4,5	13.90	14.00	14.10	4,5
E	7.95	8.10	8.25	3	7.95	8.10	8.25	3
E1	6.00	6.10	6.20	4,6	6.00	6.10	6.20	4,6
N	48				56			

LAND PATTERN DIMENSIONS



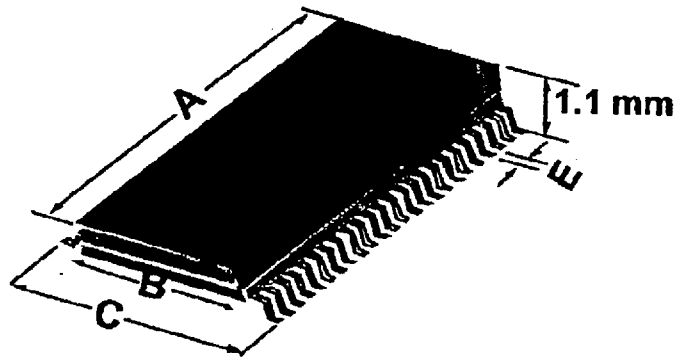
	MIN	MAX	MIN	MAX
P	8.90	9.10	8.90	9.10
P1	5.90	6.10	5.90	6.10
P2	11.50 BSC		13.50 BSC	
X	.30	.40	.30	.40
e	.50 BSC		.50 BSC	
N	48		56	

NOTES:

1. ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
2. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-
3. DIMENSION E TO BE DETERMINED AT SEATING PLANE -C-
4. DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE -H-
5. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
6. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
7. DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
8. LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
10. ALL DIMENSIONS ARE IN MILLIMETERS
11. THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION ED & EE

TOLERANCES UNLESS SPECIFIED		Integrated Device Technology, Inc.
DECIMAL ANGULAR		2975 Stender Way, Santa Clara, CA 95054
XX± ±		PHONE: (408) 727-6116
XXX±		FAX: (408) 492-8674 TWX: 910-338-2070
XXXX±		
APPROVALS	DATE	TITLE PA PACKAGE OUTLINE 6.10 mm BODY WIDTH TSSOP .50 mm PITCH
DRAWN AA	01/13/93	
CHECKED		SIZE C DRAWING No. PSC-4039 REV 03
		DO NOT SCALE DRAWING

TVSOP
The Most Compact Double Density Package



TVSOP Package	Typical Dimensions (in mm)				Area (mm2)
	A	B	C	E	
48 Pin	9.80	4.40	6.40	0.40	63.00
56 Pin	11.30	4.40	6.40	0.40	72.30
80 Pin	17.00	6.10	8.10	0.40	137.80
100 Pin	20.80	6.10	8.10	0.40	168.50

Double Density Packaging

48-Pin

16.0 x 10.3 x 2.6 mm
pin pitch = 0.635 mm
Area = 164.8 mm²

12.5 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 101.3 mm²

9.8 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 62.7 mm²

56-Pin

18.4 x 10.3 x 2.6 mm
pin-pitch = 0.635 mm
Area = 189.5 mm²

14.0 x 8.1 x 1.1 mm
pin-pitch = 0.5 mm
Area = 113.4 mm²

11.3 x 6.4 x 1.1 mm
pin-pitch = 0.4 mm
Area = 72.3 mm²

TVSOP	Area (mm^2)	%Smaller Than SSOP	%Smaller Than TSSOP
48 pin	63.00	61.9	38.0
56 pin	72.30	62.2	36.0